## **APPLICATION DATA SHEET**

## Electronic Version v14

## Stylesheet Version v14.0

Title of Invention

PROBE TIP DESIGN APPLIED IN A FLIP CHIP PACKAGING PROCESS

Application Type : regular, utility
Attorney Docket Number : NAUP0520USA

Correspondence address:

Customer Number: 027765

Inventors Information:

Inventor 1:

**Applicant Authority Type:** Inventor **Citizenship:** TW

Given Name: Hung-Min

Family Name: Liu

Residence:

City of Residence: Hsin-Chu City

Country of Residence: TW

**Address-1 of Mailing Address:** 4F, No. 30, Lane 81, Ta-Hsueh Rd.

Address-2 of Mailing Address:

City of Mailing Address: Hsin-Chu City

State of Mailing Address:

**Postal Code of Mailing Address:** 

Country of Mailing Address: TW

Phone: Fax:

E-mail:

Inventor 2:

**Applicant Authority Type:** Inventor **Citizenship:** TW

Given Name: Kow-Bao Chen

Residence:

City of Residence: Hsin-Chu City

Country of Residence: TW

Address-1 of Mailing Address: No. 11, Lane 156, Nan-Ya St.

Address-2 of Mailing Address:

City of Mailing Address: Hsin-Chu City

**State of Mailing Address:** 

**Postal Code of Mailing Address:** 

Country of Mailing Address: TW

Phone:

Fax:

E-mail:

Attorney Information:

practitioner(s) at Customer Number:

027765



as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.